

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10563463
<b>Filing Date:</b>	05-Jan-2006
<b>Title of Invention:</b>	CUCURBITURIL DERIVATIVE-BONDED SOLID SUBSTRATE AND BIOCHIP USING THE SAME
<b>First Named Inventor/Applicant Name:</b>	Kimoon Kim
<b>Filer:</b>	Joseph A. Hynds/wendy carballo
<b>Attorney Docket Number:</b>	1751-393

Filed as Small Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	2501	1	755	755
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	5	3	15
<b>Total in USD (\$)</b>				<b>1070</b>